



## Material Content Data Sheet



Halogen-Free

<b>Sales Product Name</b>	ISZ0702NLS	<b>Issued</b>	17. May 2021
<b>MA#</b>	MA005423352		
<b>Package</b>	PG-TSDSON-8-25	<b>Weight*</b>	35.65 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.463	1.30	1.30	12995	12995
leadframe	inorganic material	phosphorus	7723-14-0	0.002	0.01		69	
	non noble metal	zinc	7440-66-6	0.010	0.03		276	
	non noble metal	iron	7439-89-6	0.197	0.55		5519	
	non noble metal	copper	7440-50-8	7.988	22.41	23.00	224108	229972
wire	noble metal	gold	7440-57-5	0.028	0.08	0.08	784	784
encapsulation	organic material	carbon black	1333-86-4	0.038	0.11		1059	
	plastics	epoxy resin	-	1.944	5.45		54547	
	inorganic material	silicondioxide	60676-86-0	16.895	47.40	52.96	473971	529577
leadfinish	non noble metal	tin	7440-31-5	0.395	1.11	1.11	11089	11089
plating	noble metal	silver	7440-22-4	0.020	0.06	0.06	570	570
solder	non noble metal	tin	7440-31-5	0.014	0.04		399	
	noble metal	silver	7440-22-4	0.018	0.05		499	
	non noble metal	lead	7439-92-1	0.680	1.91	2.00	19070	19968
heat sink clip	inorganic material	phosphorus	7723-14-0	0.001			26	
	non noble metal	zinc	7440-66-6	0.004	0.01		102	
	non noble metal	iron	7439-89-6	0.073	0.20		2045	
	non noble metal	copper	7440-50-8	2.959	8.30	8.51	83017	85190
heatspreader	inorganic material	phosphorus	7723-14-0	0.001			33	
	non noble metal	zinc	7440-66-6	0.005	0.01		132	
	non noble metal	iron	7439-89-6	0.094	0.26		2637	
	non noble metal	copper	7440-50-8	3.816	10.71	10.98	107053	109855
*deviation	< 10%	Sum in total:				100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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